

# Flipping Bits in Memory Without Accessing Them:

## An Experimental Study of DRAM Disturbance Errors

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\*Work done while at Carnegie Mellon University

*ISCA 2014*

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# Problem

# Problem

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- The continued scaling of DRAM process technology has enabled smaller cells to be placed closer to each other
- This gives us:
  - Increase of cells per unit area
  - Decrease of cost per bit memory
- But also:
  - Reduced noise margin, more vulnerable to data loss
  - Electromagnetic coupling effects between cells
  - Higher variation in process technology increases number of outlier cells

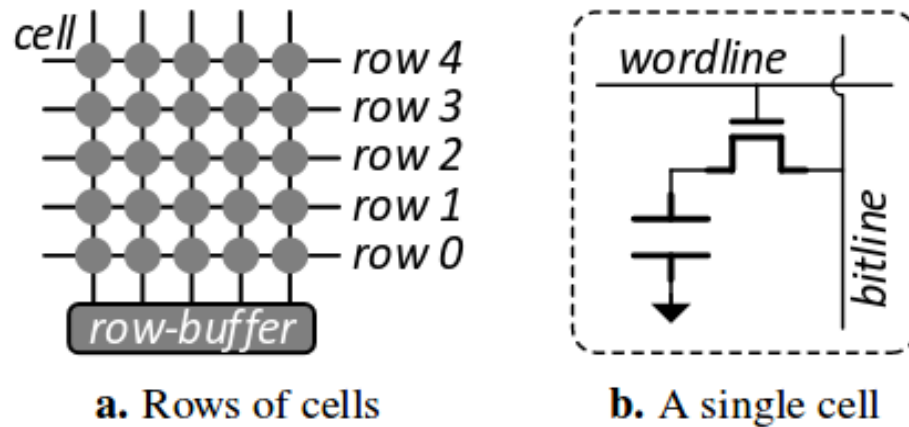
# Problem

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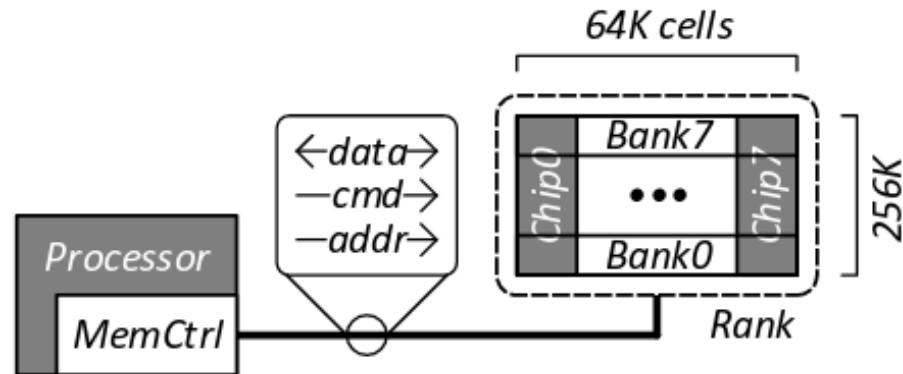
- As a result, high-density DRAM is more likely to suffer from *disturbance*, a phenomenon in which different cells interfere with each other's operation.
- If a cell is disturbed beyond its noise margin, it malfunctions and experiences a *disturbance error*.

# Background

# DRAM Cell



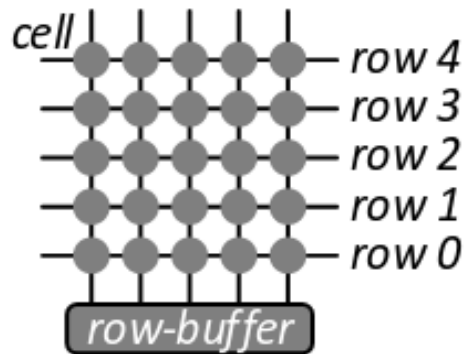
**Figure 1.** DRAM consists of cells



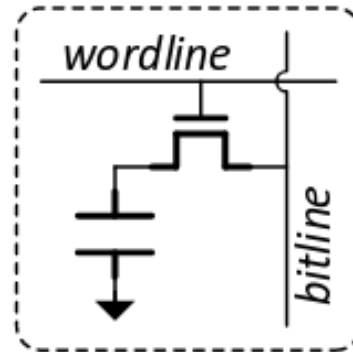
**Figure 2.** Memory controller, buses, rank, and banks

# DRAM Access & Refresh

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a. Rows of cells



b. A single cell

- **Open Row:** raise wordline, transfer data into row-buffer
- **Read/Write:** access row-buffer's data
- **Close Row:** lower wordline, clear row-buffer
  
- **Refresh:** restore the charge in cells (DDR3 ~ 64ms, can also be achieved by opening a row)

# Goal



# Goal

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- Expose the existence and the widespread nature of disturbance errors in commodity DRAM chips sold and used "today" (2014).

# Novelty, Key Approach, and Ideas

# Novelty

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- Demonstrates the existence of DRAM disturbance errors on real systems using DRAM devices
  - Known as „RowHammer“
- Extensively characterizes these errors using FPGA-based testing platform
- Proposes and explores various solutions to prevent DRAM disturbance errors and shows a novel, low-cost system-level approach

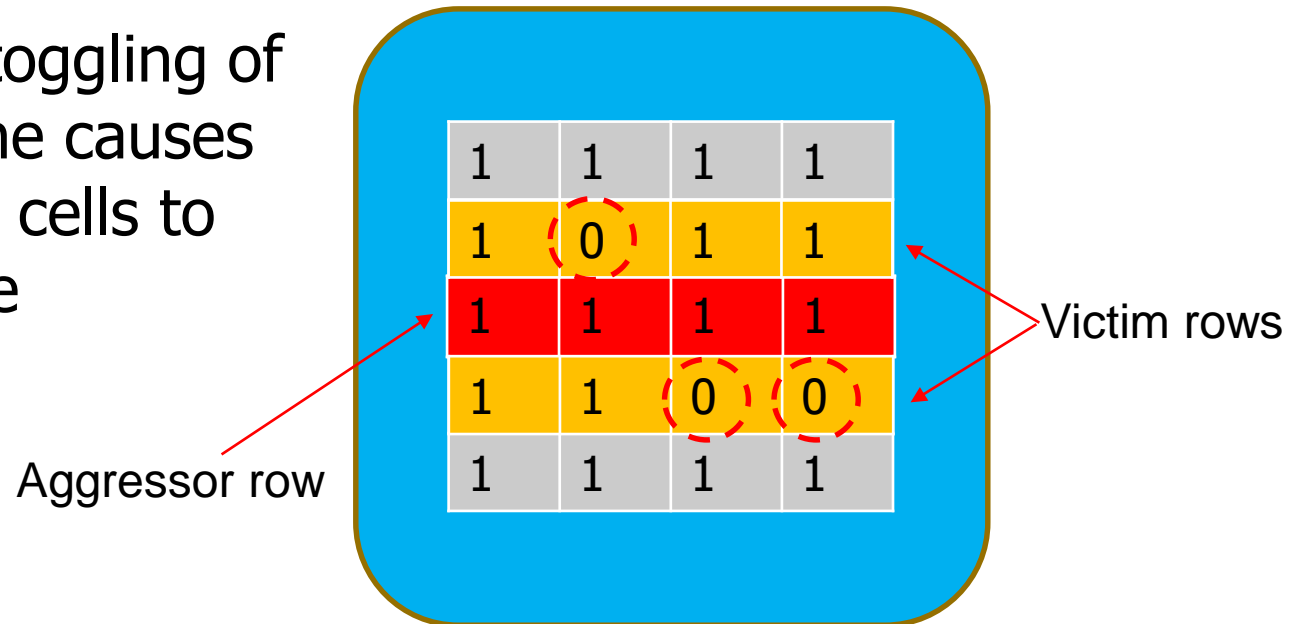
# Key-Ideas & Approach

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- Causes of Disturbance Errors
  - Electromagnetic coupling
    - Toggling the wordline voltage briefly increases the voltage of adjacent wordlines, this slightly opens adjacent rows -> Leakage of charge
  - Conductive bridges
  - Hot-carrier injection

# Toggling the wordline

- Repeated toggling of the wordline causes the nearby cells to leak charge



# Mechanisms

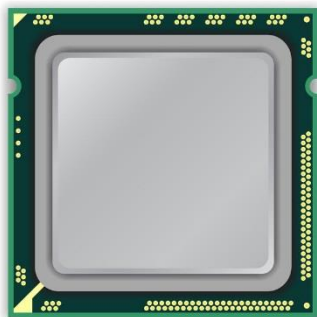
# How to Induce Errors

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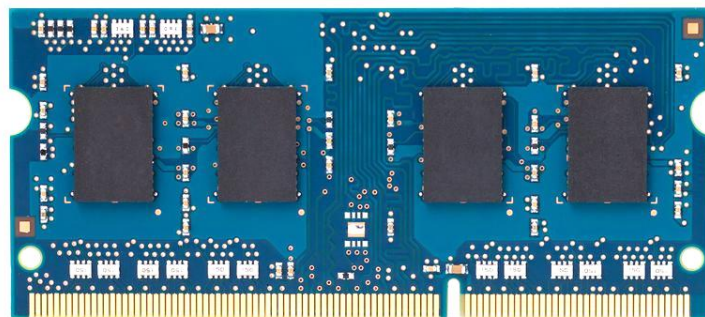
- Is it that simple?
  - No!
- 1. Avoid cache hits
  - Flush X from cache
- 2. Avoid row hits to X
  - Read Y in another row

# How to Induce Errors

x86 CPU



DRAM Module



```
loop:  
  mov  (X), %eax  
  mov  (Y), %ebx  
  clflush (X)  
  clflush (Y)  
  mfence  
  jmp  loop
```

	001110111
X →	1111   1111
	101111101
	110001011
Y →	1111   1111
	011011110



**Key Results:**

**Methodology and Evaluation**

# Methodology

- 8 FPGA boards with DDR3 DRAM memory controller
- Tested 129 DRAM modules from manufactures A, B and C, with capacities from 512MB-2GB and production year '08-14

```
1 TESTBULK(AI, RI, DP)
2   setAI(AI)
3   setRI(RI)
4    $N \leftarrow (2 \times RI) / AI$ 
5
6   writeAll(DP)
7   for  $r \leftarrow 0 \dots ROW_{MAX}$ 
8     for  $i \leftarrow 0 \dots N$ 
9       ACT  $r^{th}$  row
10      READ  $0^{th}$  col.
11      PRE  $r^{th}$  row
12   readAll()
13   findErrors()
```

a. Test all rows at once

```
1 TESTEACH(AI, RI, DP)
2   setAI(AI)
3   setRI(RI)
4    $N \leftarrow (2 \times RI) / AI$ 
5
6   for  $r \leftarrow 0 \dots ROW_{MAX}$ 
7     writeAll(DP)
8     for  $i \leftarrow 0 \dots N$ 
9       ACT  $r^{th}$  row
10      READ  $0^{th}$  col.
11      PRE  $r^{th}$  row
12   readAll()
13   findErrors()
```

b. Test one row at a time

## Access Interval (AI)

- Time between two accesses

## Refresh Interval (RI)

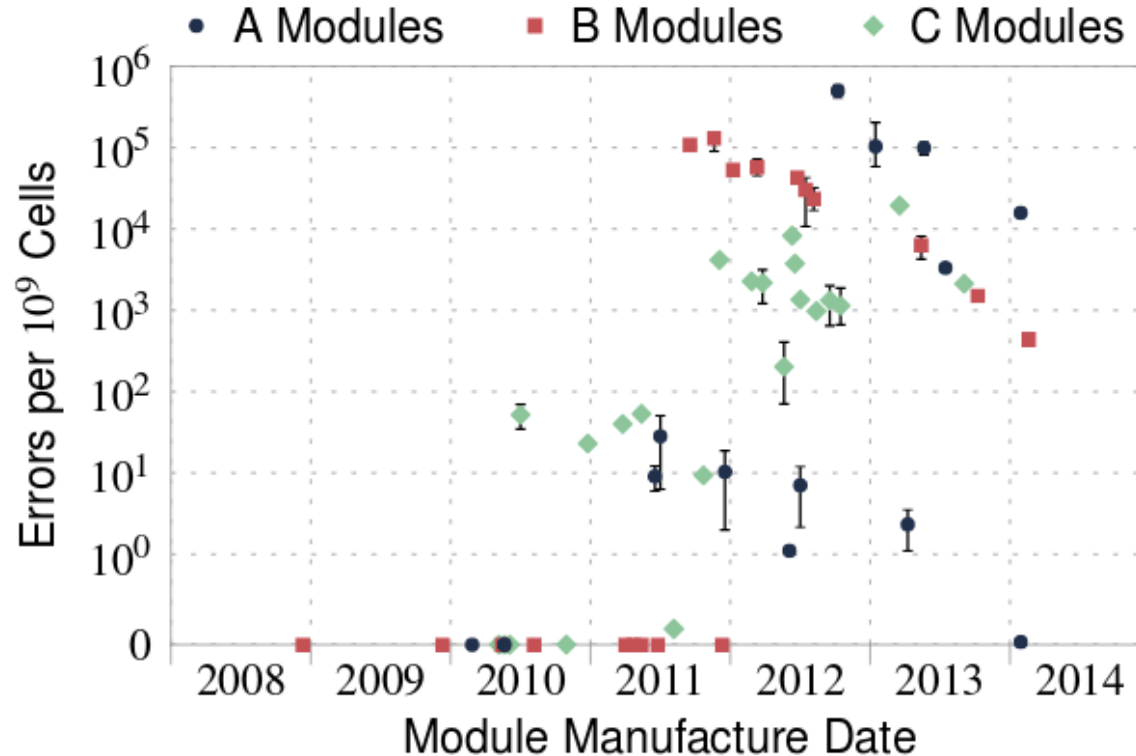
- Time between two refreshes

## Data Pattern (DP)

- Data stored in DRAM
- e.g. RowStripe (~RowStripe) alternate rows 1s and 0s

# Disturbance Errors are Widespread

- Most modules are at risk
  - In 110 / 129 tested modules they were able to induce errors
- The modules without errors were built before 2012 (except one)



# Error = Charge Loss

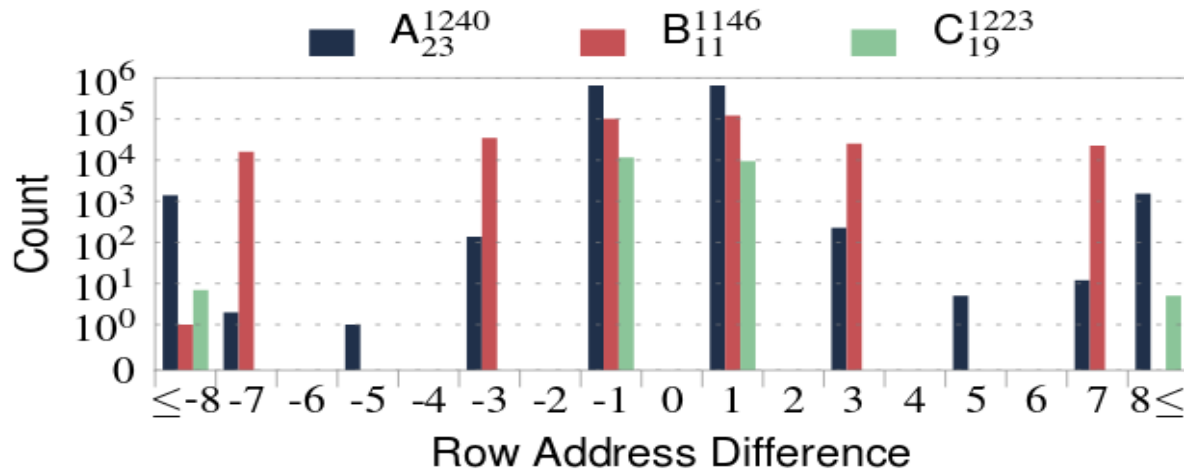
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- Two types of errors
  - - '1' -> '0' and '0' -> '1'
- A given cell suffers only one type
- Two types of cells (chosen by manufacturer)
  - True-cell: Charged = 1 -> only '1' -> '0' errors
  - Anti-cell: Charged = 0 -> only '0' -> '1' errors
- Errors are a loss of charge
  
- Example module from A:

Bit-Flip	Sandy Bridge	Ivy Bridge	Haswell	Piledriver
'0' → '1'	7,992	10,273	11,404	47
'1' → '0'	8,125	10,449	11,467	12

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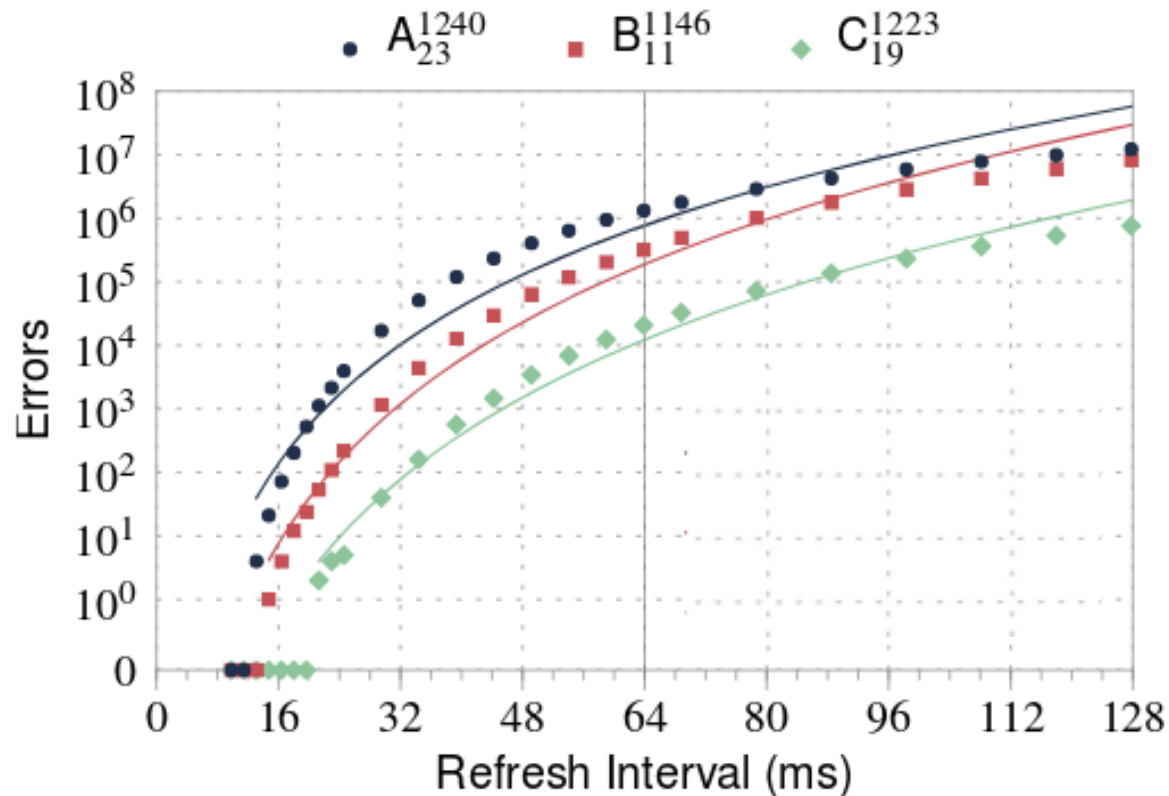
# Address Correlation



- Peaks at +/- 1
- But why this distribution?
  - Physical address may differ from logical address
  - Fault rows are often re-mapped to spare rows
  - Aggressor row can affect more than two rows

# Sensitivity

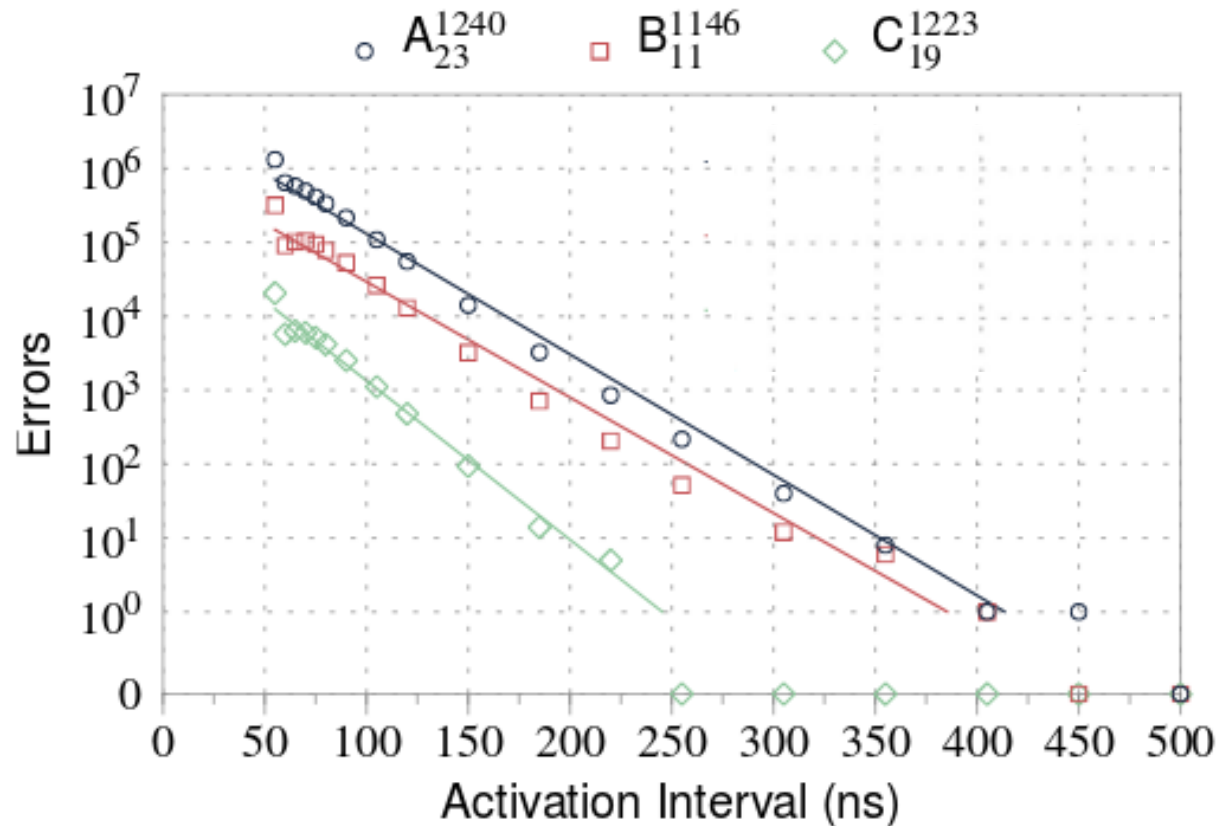
- Shorter RI -> fewer errors



- To eliminate all disturbance errors the refresh interval must be shortened by 7x for the worst module

# Sensitivity

- Longer AI -> fewer errors



# Sensitivity

- Errors also dependent on data stored in other cells

Solid	RowStripe	ColStripe	Checkered
111111	111111	101010	101010
111111	000000	101010	010101
111111	111111	101010	101010
111111	000000	101010	010101

<i>Module</i>	TESTBULK( $DP$ ) + TESTBULK( $\sim DP$ )			
	Solid	RowStripe	ColStripe	Checkered
$A_{23}$	112,123	<b>1,318,603</b>	763,763	934,536
$B_{11}$	12,050	<b>320,095</b>	9,610	302,306
$C_{19}$	57	20,770	130	<b>29,283</b>

- RowStripe causes  $\sim 10x$  more errors than Solid



# Error Correction Code - ECC

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- Couldn't we just use simple Error Correction Codes as SECDED?
  - SECDED (:= Single Error Correction, Double Error-Detection) detects up to two errors and can correct one error
- How many errors per row?

<i>Module</i>	<i>Number of 64-bit words with X errors</i>			
	<i>X = 1</i>	<i>X = 2</i>	<i>X = 3</i>	<i>X = 4</i>
A <sub>23</sub>	9,709,721	<b>181,856</b>	<b>2,248</b>	<b>18</b>
B <sub>11</sub>	2,632,280	<b>13,638</b>	<b>47</b>	0
C <sub>19</sub>	141,821	<b>42</b>	0	0

- SECDED is not safe!

# Other results

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- Victim Cells  $\neq$  Weak Cells
  - Weak cells  $:=$  Cells with the shortest retention times
- Errors are repeatable, but needs a lot of testing time
- Errors are almost independent of temperature change
- Some cells have two aggressors

# Possible Solutions

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- Make better chips
  - ... depends on process technology
- Correct errors
  - ... multibit errors and overhead
- Refresh all rows frequently
  - ... shorten RI -> overhead and performance
- Retire cells (manufacturer)
  - ... exhaustive search, many spare cells required
- Retire cells (end-user)
  - ... end-user pays for identifying and remapping
- Identify hot rows, refresh neighbours
  - ... counters needed, complex, costs

# Proposed Solution

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- PARA (Probabilistic Adjacent Row Activation)
  - Idea:
    - When a row is open/closed, an adjacent row is opened with small probability
  - Mechanism:
    - When a row is closed, flip a biased coin ( $p \ll 1$ )
    - If head, refresh one of the two adjacent row
  - Problem:
    - Needs to know how logical mapping is done by manufacturer
  - Advantages:
    - Refreshes row infrequently (low power & performance-overhead)
    - Stateless (low cost & low complexity)

# Summary

# Summary

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- Problem:
  - High-density DRAM is more likely to suffer from disturbance
- Goal:
  - Expose the existence and the widespread nature of disturbance errors in commodity DRAM chips
- Key results:
  - 110 out of 129 modules were vulnerable
  - Root cause: repeated toggling of a wordline
- Conclusion:
  - Disturbance errors are an emerging problem
  - Many deployed systems could be at risk

# Strengths

# Strengths

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- The first paper to expose the widespread existence of disturbance errors in DRAM chips
  - Is the basis for a lot of further work (321 citations)
- Identifies a new reliability problem and a security vulnerability, RowHammer, that affects an entire generation of computing systems being used today
  - RowHammer is still relevant today!
- Real-system approach, not only theoretical
- With PARA a neat solution is provided
- Clear structured paper, worth reading, if you want to understand further papers on RowHammer



# Weaknesses

# Weaknesses

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- Assumes the existence of security exploits, but just touches the topic and doesn't provide a working example.
- Paper is limited to x86-architecture.

- Paper relies on the memory controller flipping a coin. If the outcome of the coin flip could be predicted by an attacker in advance, the attack could be avoided.

Bit-Flip	Sandy Bridge	Ivy Bridge	Haswell	Piledriver
'0' → '1'	7,992	10,273	11,404	47
'1' → '0'	8,125	10,449	11,467	12

- Difference between # of bitflips with AMD and Intel processors is just explained in a footnote and limited to speed

# Thoughts and Ideas

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- What about RowHammer today?
  - Google Project Zero exploited the DRAM RowHammer bug to gain kernel privileges
  - Recent studies and reports also suggest vulnerability of DDR4 Ram, mobilephones (ARM), GPU of mobilephones and RowHammer Attacks over the Network.
  - "Solutions": Shorten RI to 32ms, ECC, TRR and restrict cflush
- What about ARM / Mobile platform? What about SRAM, flash and harddisk?
  - ARM --> Drammer: Deterministic Rowhammer Attacks on Mobile Platforms [V. van der Veen et al., 2016]
  - NAND Flash --> Read Disturb Errors in MLC NAND Flash Memory: ... [Y. Cai, O.Mutlu, et al. 2015]

# Takeaways

# Key Takeaways

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- *"It's like breaking into an apartment by repeatedly slamming a neighbor's door until the vibrations open the door you were after"* (Slides of O.Mutlu)
- RowHammer is a real issue - Disturbance errors are widespread!
- The fact that computer parts are getting smaller and smaller and the associated problems including RowHammer should receive much more attention than it currently enjoys.
- Technological progress in manufacturing technology and the scale down to smaller dimensions can produce unexpected errors that one wouldn't think of.

# Questions / Open Discussion

# Discussion

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- Is shortening the refresh interval (and or lengthen the activation interval) a practical approach?
- Is it very likely for a normal application to hammer a row accidentally?
- Is PARA enough? Do you have other solutions in mind?
- How would you implement such a coin flip used in PARA?
- Was this paper a roadmap for hackers?



# Additional Slides

# Additional papers and webpages

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- [Rowhammer.js: A Remote Software-Induced Fault Attack in JavaScript](#) [D. Gruss et al. 2015]
- [Throwhammer: Rowhammer Attacks over the Network and Defenses](#) [A. Tatar et al. 2018]
- DDR4: <http://www.thirdio.com/rowhammer.pdf>
- [Exploiting the DRAM rowhammer bug to gain kernel privileges](#) [Mark Seaborn, et al.2015]
- [Read Disturb Errors in MLC NAND Flash Mermory: ...](#) [Y. Cai, O.Mutlu, et al. 2015]
- [ANVIL: Software-Based Protection Agains Next-Generation Rowhammer Attacks](#) [Z. Aweke et al., 2016]
- [Grand Pwning Unit: Accelerating Microarchitectural Attacks with the GPU](#) [P. Frigo et al. 2018]
- [Drammer: Deterministic Rowhammer Attacks on Mobile Platforms](#) [V. van der Veen et al., 2016]
- [A New Approach for Rowhammer Attacks](#) [R. Qiao, M.Seaborn]

# Additional slides

Manufacturer	Module	Date*	Timing <sup>†</sup>		Organization		Chip			Victims-per-Module			RI <sub>th</sub> (ms)	
		(yy-ww)	Freq (MT/s)	t <sub>RC</sub> (ns)	Size (GB)	Chips	Size (Gb) <sup>‡</sup>	Pins	DieVersion <sup>§</sup>	Average	Minimum	Maximum	Min	
C Total of 32 Modules	C <sub>1</sub>	10-18	1333	49.125	2	8	2	×8	A	0	0	0	–	
	C <sub>2</sub>	10-20	1066	50.625	2	8	2	×8	A	0	0	0	–	
	C <sub>3</sub>	10-22	1066	50.625	2	8	2	×8	A	0	0	0	–	
	C <sub>4-5</sub>	10-26	1333	49.125	2	8	2	×8	B	8.9 × 10 <sup>2</sup>	6.0 × 10 <sup>2</sup>	1.2 × 10 <sup>3</sup>	29.5	
	C <sub>6</sub>	10-43	1333	49.125	1	8	1	×8	T	0	0	0	–	
	C <sub>7</sub>	10-51	1333	49.125	2	8	2	×8	B	4.0 × 10 <sup>2</sup>	4.0 × 10 <sup>2</sup>	4.0 × 10 <sup>2</sup>	29.5	
	C <sub>8</sub>	11-12	1333	46.25	2	8	2	×8	B	6.9 × 10 <sup>2</sup>	6.9 × 10 <sup>2</sup>	6.9 × 10 <sup>2</sup>	21.3	
	C <sub>9</sub>	11-19	1333	46.25	2	8	2	×8	B	9.2 × 10 <sup>2</sup>	9.2 × 10 <sup>2</sup>	9.2 × 10 <sup>2</sup>	27.9	
	C <sub>10</sub>	11-31	1333	49.125	2	8	2	×8	B	3	3	3	39.3	
	C <sub>11</sub>	11-42	1333	49.125	2	8	2	×8	B	1.6 × 10 <sup>2</sup>	1.6 × 10 <sup>2</sup>	1.6 × 10 <sup>2</sup>	39.3	
	C <sub>12</sub>	11-48	1600	48.125	2	8	2	×8	C	7.1 × 10 <sup>4</sup>	7.1 × 10 <sup>4</sup>	7.1 × 10 <sup>4</sup>	19.7	
	C <sub>13</sub>	12-08	1333	49.125	2	8	2	×8	C	3.9 × 10 <sup>4</sup>	3.9 × 10 <sup>4</sup>	3.9 × 10 <sup>4</sup>	21.3	
	C <sub>14-15</sub>	12-12	1333	49.125	2	8	2	×8	C	3.7 × 10 <sup>4</sup>	2.1 × 10 <sup>4</sup>	5.4 × 10 <sup>4</sup>	21.3	
	C <sub>16-18</sub>	12-20	1600	48.125	2	8	2	×8	C	3.5 × 10 <sup>3</sup>	1.2 × 10 <sup>3</sup>	7.0 × 10 <sup>3</sup>	27.9	
	C <sub>19</sub>	12-23	1600	48.125	2	8	2	×8	E	1.4 × 10 <sup>5</sup>	1.4 × 10 <sup>5</sup>	1.4 × 10 <sup>5</sup>	18.0	
	C <sub>20</sub>	12-24	1600	48.125	2	8	2	×8	C	6.5 × 10 <sup>4</sup>	6.5 × 10 <sup>4</sup>	6.5 × 10 <sup>4</sup>	21.3	
	C <sub>21</sub>	12-26	1600	48.125	2	8	2	×8	C	2.3 × 10 <sup>4</sup>	2.3 × 10 <sup>4</sup>	2.3 × 10 <sup>4</sup>	24.6	
	C <sub>22</sub>	12-32	1600	48.125	2	8	2	×8	C	1.7 × 10 <sup>4</sup>	1.7 × 10 <sup>4</sup>	1.7 × 10 <sup>4</sup>	22.9	
	C <sub>23-24</sub>	12-37	1600	48.125	2	8	2	×8	C	2.3 × 10 <sup>4</sup>	1.1 × 10 <sup>4</sup>	3.4 × 10 <sup>4</sup>	18.0	
	C <sub>25-30</sub>	12-41	1600	48.125	2	8	2	×8	C	2.0 × 10 <sup>4</sup>	1.1 × 10 <sup>4</sup>	3.2 × 10 <sup>4</sup>	19.7	
	C <sub>31</sub>	13-11	1600	48.125	2	8	2	×8	C	3.3 × 10 <sup>5</sup>	3.3 × 10 <sup>5</sup>	<b>3.3 × 10<sup>5</sup></b>	<b>14.7</b>	
	C <sub>32</sub>	13-35	1600	48.125	2	8	2	×8	C	3.7 × 10 <sup>4</sup>	3.7 × 10 <sup>4</sup>	3.7 × 10 <sup>4</sup>	21.3	
	B Total of 54 Modules	B <sub>8</sub>	11-23	1333	49.125	2	8	2	×8	C	0	0	0	–
		B <sub>9</sub>	11-37	1333	49.125	2	8	2	×8	D	1.9 × 10 <sup>6</sup>	1.9 × 10 <sup>6</sup>	1.9 × 10 <sup>6</sup>	11.5
		B <sub>10-12</sub>	11-46	1333	49.125	2	8	2	×8	D	2.2 × 10 <sup>6</sup>	1.5 × 10 <sup>6</sup>	<b>2.7 × 10<sup>6</sup></b>	11.5
		B <sub>13</sub>	11-49	1333	49.125	2	8	2	×8	C	0	0	0	–
		B <sub>14</sub>	12-01	1866	47.125	2	8	2	×8	D	9.1 × 10 <sup>5</sup>	9.1 × 10 <sup>5</sup>	9.1 × 10 <sup>5</sup>	<b>9.8</b>
		B <sub>15-31</sub>	12-10	1866	47.125	2	8	2	×8	D	9.8 × 10 <sup>5</sup>	7.8 × 10 <sup>5</sup>	1.2 × 10 <sup>6</sup>	11.5
		B <sub>32</sub>	12-25	1600	48.125	2	8	2	×8	E	7.4 × 10 <sup>5</sup>	7.4 × 10 <sup>5</sup>	7.4 × 10 <sup>5</sup>	11.5
		B <sub>33-42</sub>	12-28	1600	48.125	2	8	2	×8	E	5.2 × 10 <sup>5</sup>	1.9 × 10 <sup>5</sup>	7.3 × 10 <sup>5</sup>	11.5
		B <sub>43-47</sub>	12-31	1600	48.125	2	8	2	×8	E	4.0 × 10 <sup>5</sup>	2.9 × 10 <sup>5</sup>	5.5 × 10 <sup>5</sup>	13.1
		B <sub>48-51</sub>	13-19	1600	48.125	2	8	2	×8	E	1.1 × 10 <sup>5</sup>	7.4 × 10 <sup>4</sup>	1.4 × 10 <sup>5</sup>	14.7
B <sub>52-53</sub>		13-40	1333	49.125	2	8	2	×8	D	2.6 × 10 <sup>4</sup>	2.3 × 10 <sup>4</sup>	2.9 × 10 <sup>4</sup>	21.3	
B <sub>54</sub>	14-07	1333	49.125	2	8	2	×8	D	7.5 × 10 <sup>3</sup>	7.5 × 10 <sup>3</sup>	7.5 × 10 <sup>3</sup>	26.2		

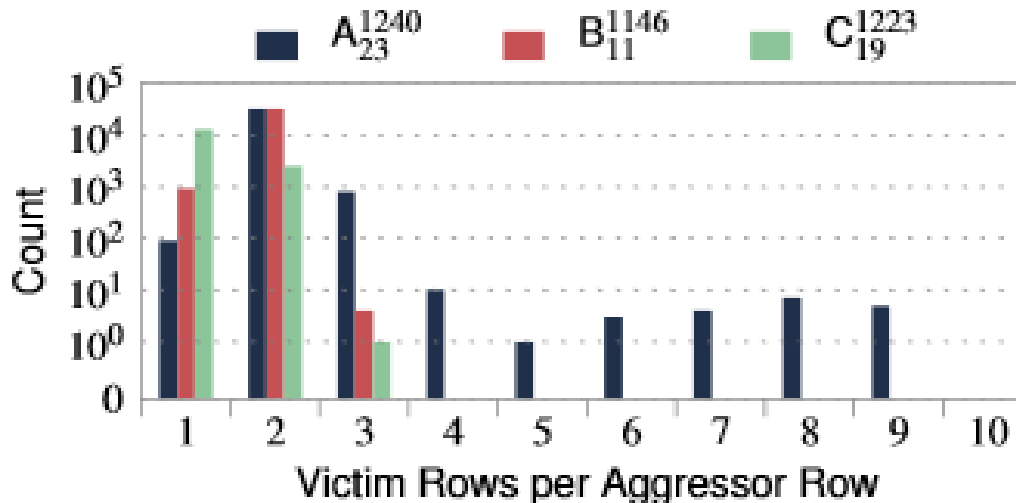
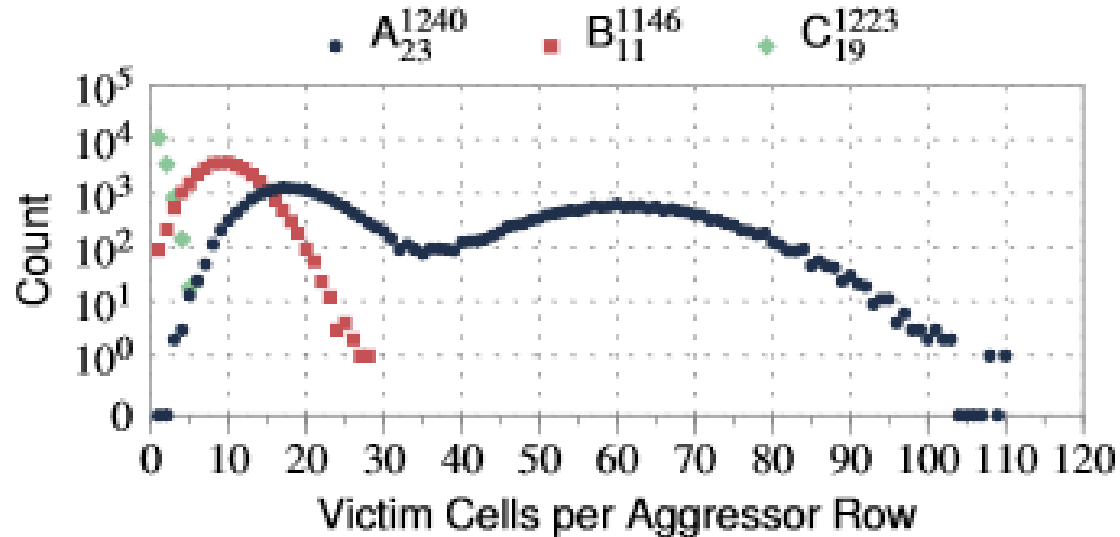
# Additional slides

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Access Pattern	Disturbance Errors?
1. $(open-read-close)^N$	<b>Yes</b>
2. $(open-write-close)^N$	<b>Yes</b>
3. $open-read^N-close$	No
4. $open-write^N-close$	No

**Table 4.** Access patterns that induce disturbance errors

# Additional slides



# Additional slides

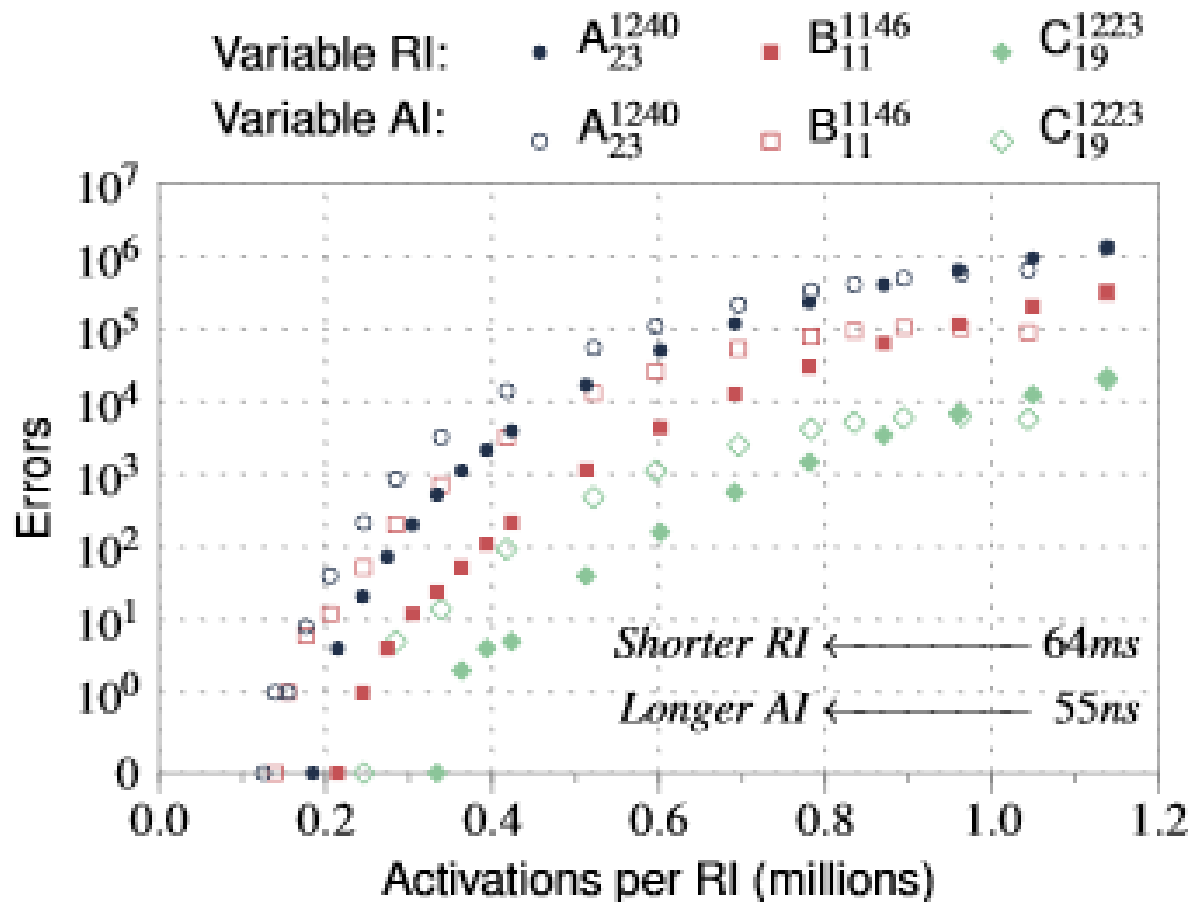
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Duration	$N_{th}=50K$	$N_{th}=100K$	$N_{th}=200K$
<i>64ms</i>	$1.4 \times 10^{-11}$	$1.9 \times 10^{-22}$	$3.6 \times 10^{-44}$
<i>1 year</i>	$6.8 \times 10^{-3}$	$9.4 \times 10^{-14}$	$1.8 \times 10^{-35}$

**Table 7.** Error probabilities for PARA when  $p=0.001$

- $N_{th}$  = open and close during a refresh interval
- Independent coin flips  $\rightarrow p_{coinflip} = (1-p/2)^{N_{th}}$

# Additional slides



**Figure 6.** Number of errors vs. number of activations